



Material Content Data Sheet



Sales Product Name		IPLU300N04S4-R8		Issued		19. January 2018		
MA#		MA001063262						
Package		PG-HSOF-8-1		Weight*		768.65 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.676	0.09		879	
	non noble metal	tin	7440-31-5	0.174	0.02		227	
	inorganic material	silicon	7440-21-3	6.482	0.84	0.95	8434	9540
leadframe	non noble metal	iron	7439-89-6	0.421	0.05		547	
	inorganic material	phosphorus	7723-14-0	0.126	0.02		164	
	non noble metal	copper	7440-50-8	420.040	54.65	54.72	546463	547174
wire	non noble metal	aluminium	7429-90-5	15.288	1.99	1.99	19889	19889
encapsulation	organic material	carbon black	1333-86-4	4.777	0.62		6214	
	plastics	epoxy resin	-	52.543	6.84		68357	
	inorganic material	silicondioxide	60676-86-0	261.120	33.97	41.43	339711	414282
leadfinish	non noble metal	tin	7440-31-5	6.479	0.84	0.84	8429	8429
plating	non noble metal	nickel	7440-02-0	0.526	0.07		684	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.07	2	686
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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